

GPON Pigtail BOSA

Model: BA-GDP121SP49

1. Features:

- Single fiber bi-di data links application with 1.244Gbps upstream and 2.488Gbps downstream.
 - 1310nm burst mode DFB transmitter and Burst On/Off time is less than 30ns;
 - 1490nm continuous mode continuous-mode Super-TIA receiver;
 - -20 to 85°C operating case temperature;
 - Package with SC/UPC Pigtail.
- RoHS Compliance for SOEB3466-FUGF.

2. Applications:

- SM Fiber bidi data links application with 1.244Gbps upstream and 2.488Gbps downstream.

3. Absolute Maximum Ratings(T=25°C):

Parameter	Symbol	Condition	Min.	Max.	Unit
LD Forward current	I _{FLD}	-	-	150	mA
LD Reverse voltage	V _{RLD}	-	-	2	V
MPD Forward current	I _{FMPD}	CW	-	2	mA
MPD Reverse voltage	V _{RMPD}	-	-	15	V
TIA Supply voltage	V _{CC}	-	-	4.5	V
Case operating temperature	T _C	-	-20	+85	°C
Ambient storage temperature	T _{STG}	-	-40	+85	°C
Operating humidity	RH	-	5	85	%
Lead soldering temperature	V _{TEC}	-	-	260/10	°C/S
ESDThreshold	-	-	-	500	V

4. Recommended Operating Conditions:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Power supply voltage	V _{CC}	3.3V±5%	3.13	3.3	3.47	V
Data rate upstream	-	-	-	1.244	-	Gbit/s
Data rate downstream	-	-	-	2.488	-	Gbit/s

5. Electro-Optical Characteristics(T=25°C, unless noted otherwise):

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Transmitter						
Threshold current	I _{TH}	CW, T _C = 25°C	-	11	15	mA
		CW, T _C =-20°C~85°C	-	-	50	
Fiber output power	P _F	CW, T _C =25°C, I _{OP} =I _{TH} +20mA	1.4	-	3.5	mW
		CW, T _C =85°C, I _{OP} =I _{TH} +20mA	1.0	-	-	
Slope efficiency drop	ΔSE	(SE(25°C)-SE(85°C))/SE(25°C)	20	-	45	%
Forward voltage	V _F	CW, T _C =25°C, I _{OP} =I _{TH} +20mA	-	1.1	1.5	V
Rise/Fall time	T _R /T _F	20%~80%	-	-	0.2	ns
Peak wavelength	λ	T _C =-40~+85°C	1300	1310	1320	nm

LD PIN	Description	PIN-TIA PIN	Description
1	Laser Anode and MPD Cathode	1	GND
2	MPD Anode	2	OUT+
3	Laser Cathode	3	Vcc
4	GND	4	Isource
		5	OUT-

7. Ordering information:BA-GDP-

XX	-X	X	X	-XX	X	XX	XX
BOSA	Name	LD Type	PD Type	Data Rate	Wavelength	Connector	PIN Array
BA	G: GPON	D: DFB	P: PIN-TIA	12: 1.25/2.5G	1:1310T/1490R	SC: SC/APC	49

Precaution:

- (1) The modules should be handled in the same manner as ordinary semiconductor device to prevent the electro-static damages. For safety keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.